



Intel(R) Power And Thermal Design Studio

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Intel Thermal Design Studio; US ECCN# EAR99

Requirements

Before the Thermal Design Studio can be used, .Net Framework must be installed.

1) Microsoft .Net Framework 4.5

- <http://www.microsoft.com/en-us/download/details.aspx?id=30653>

You will receive an error if you do not install the applications in the order listed.

2) Intel(R) Power And Thermal Design Studio installer

- Check with your Intel Thermal rep

The following application is only required in order to use the Intel Virtual Sensor Estimation engine or the Thermal Curve Fitter when building new platform characterizations.

3) Matlab's Compiler Runtime v2014a

- <http://www.mathworks.com/products/compiler/mcr/index.html>

Known Issues (Items affecting accuracy)

Detailed CFD model accuracy

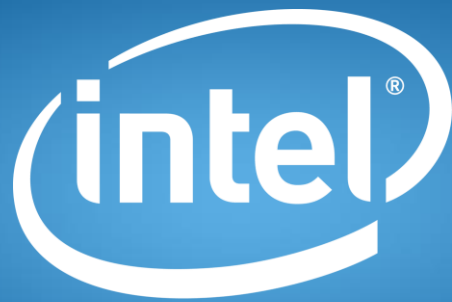
- TDS simulator engine relies on results from detailed CFD models. If the material parameters or geometry are slightly off in the CFD model it will affect the results of the TDS simulator

Curve fitting error

- TDS simulator engine relies on curve fits from the detailed CFD model results. Any errors in the curve fits will introduce errors into the transient calculator results.

Super-Positioning of Thermal Resistance

- TDS simulator engine relies on a technique of super positioning the effect of all the heat sources in the system. The model assumes heat can leave the system at the same rate that it is added. This results in faster cool down predictions than will be in an actual device.



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